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(54) **PRINTED CIRCUIT BOARD**

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(57) **ABSTRACT**

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A printed circuit board includes a first substrate portion including a first insulating layer, a second insulating layer disposed on the first insulating layer, and a third insulating layer disposed on the second insulating layer; and a second substrate portion disposed on the first substrate portion and including a first fine insulating layer as a build-up insulating layer on an uppermost side of the first substrate portion and the second substrate portion. A thickness of the first insulating layer, a thickness of the second insulating layer, and a thickness of the third insulating layer are sequentially reduced. A thickness of the first fine insulating layer is lower than the thickness of the third insulating layer.

